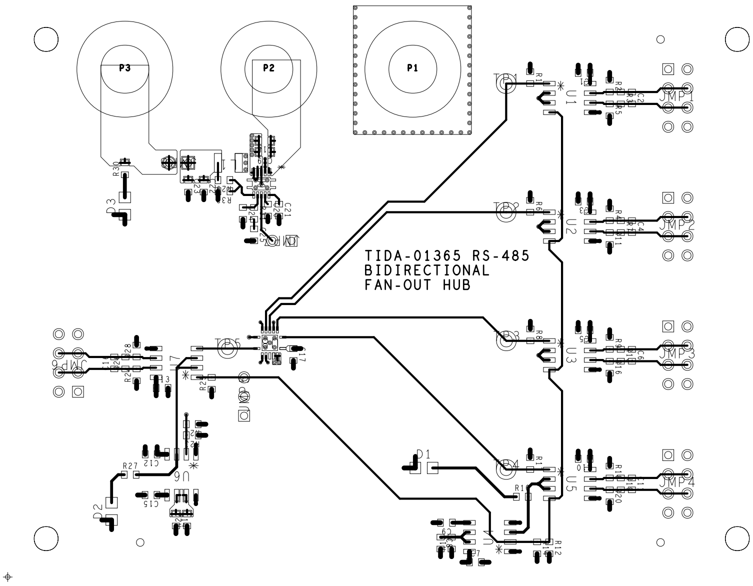
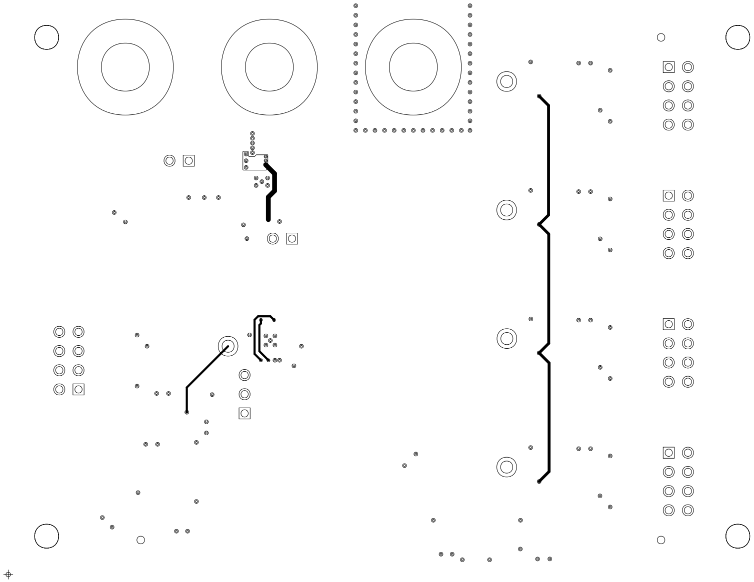
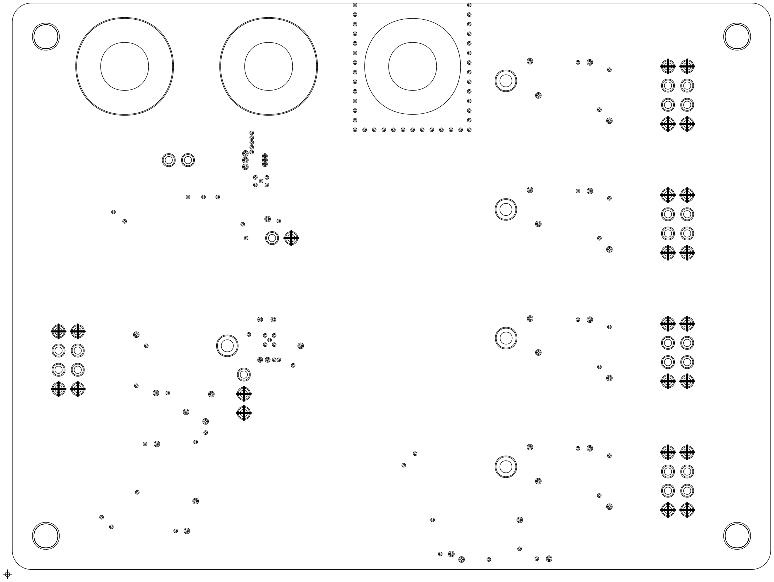


krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: XLXAXYXEXRX X1X X-X XTXOXPX XSXIXDXEX		

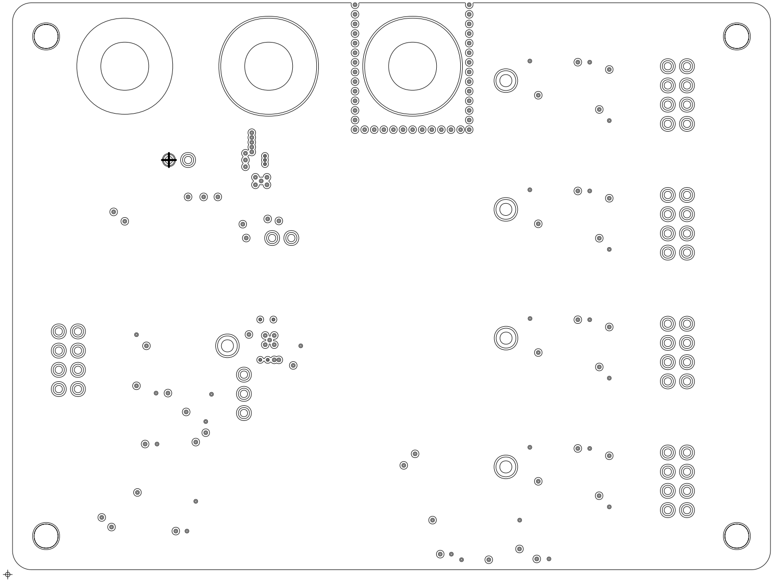


krypton solutions

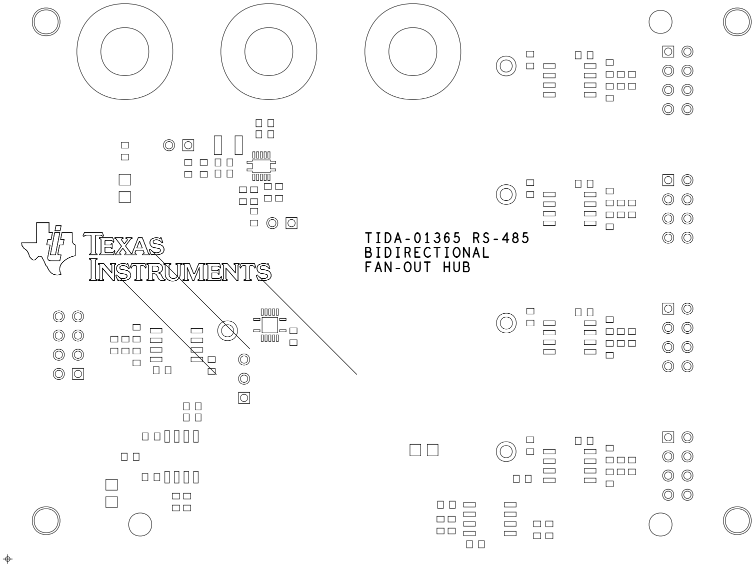
krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 4 - BOTTOM SIDE		



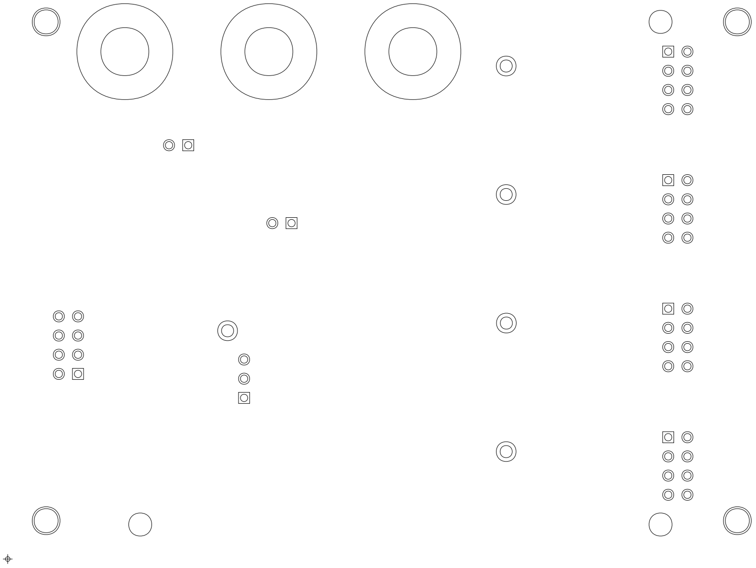
krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 2 - GND PLANE		



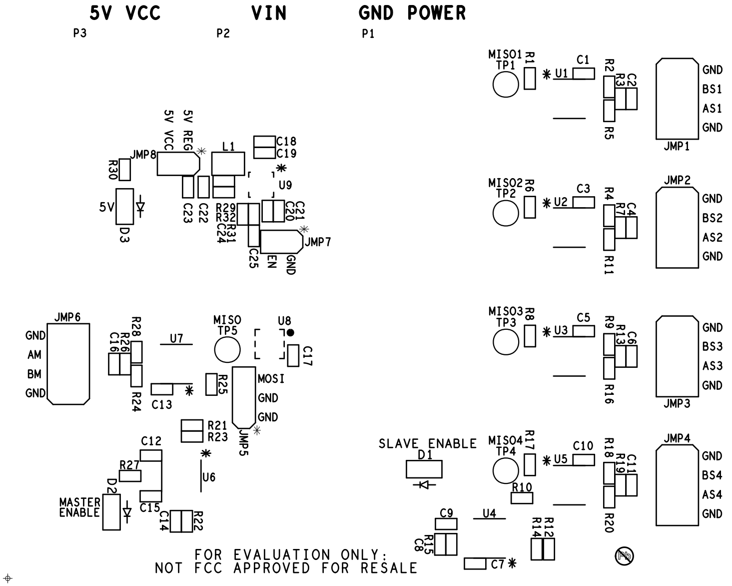
krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: LAYER 3 - PWR PLANE		



krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: XSXOXLXDXEXRXMXAXSXKX XTXOXPX X X X X		



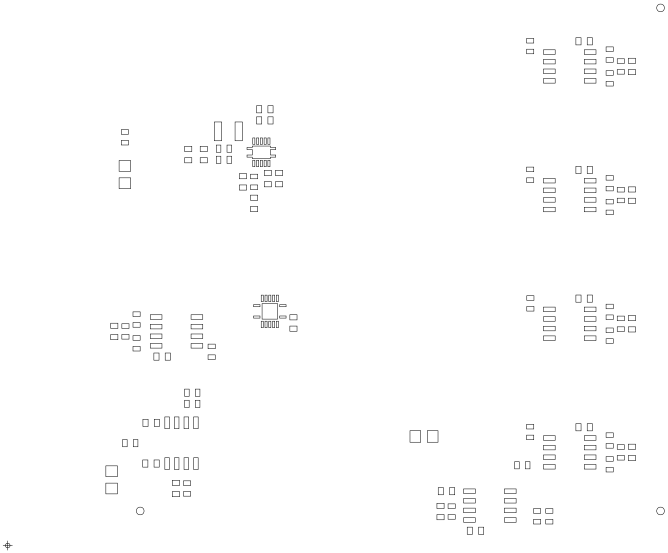
krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: SOLDERMASK_BOTTOM		



krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: SILKSCREEN TOP XXXX		

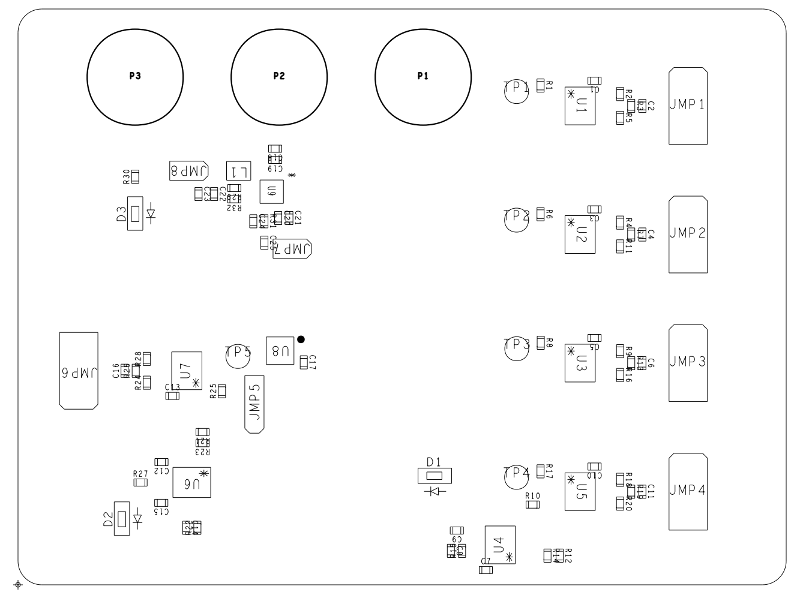
S/N: ☐

krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: SILKSCREEN BOTTOM		



krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: PASTEMASK_TOP		

krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: PASTEMASK BOTTOM		



Krypton solutions

CUSTOMER
XXXXXXXXXXXX

ENGINEER
XXXXX

BOARD NAME : XXXXXXXXXXXXXXX

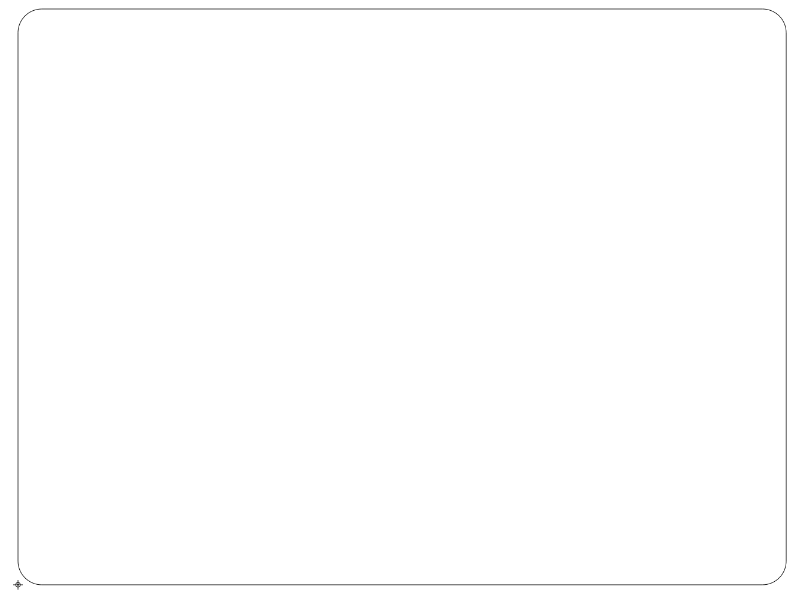
ASSEMBLY DRAWING (TOP SIDE)

APPROVALS	DATE
DRAWN: XXX	XX-XX-XX
RELEASED: XXX	XX-XX-XX
DO NOT SCALE DRAWING	

SIZE	KSID NO.	JOB NO.	REV.
D	XXXXX	XXXXXX	1.0

SCALE NONE

SHEET 1 OF 2



krypton
solutions

CUSTOMER XXXXXXXXXXXX	ENGINEER XXXXX

BOARD NAME : XXXXXXXXXXXXXXX

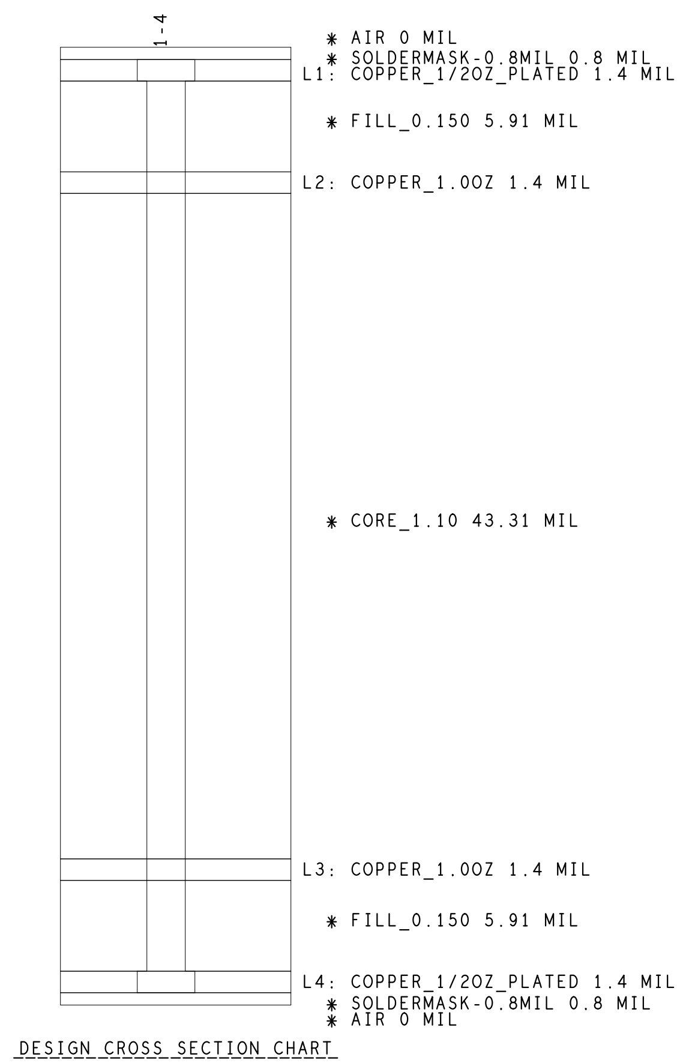
ASSEMBLY DRAWING (BOTTOM SIDE)

APPROVALS	DATE
DRAWN: XXX	XX-XX-XX
RELEASED: XXX	XX-XX-XX
DO NOT SCALE DRAWING	

SIZE	KSID NO.	JOB NO.	REV.
D	XXXXX	XXXXXX	1.0

SCALE NONE

SHEET 2 OF 2



DESIGN CROSS SECTION CHART
TOTAL THICKNESS 62.33 MIL

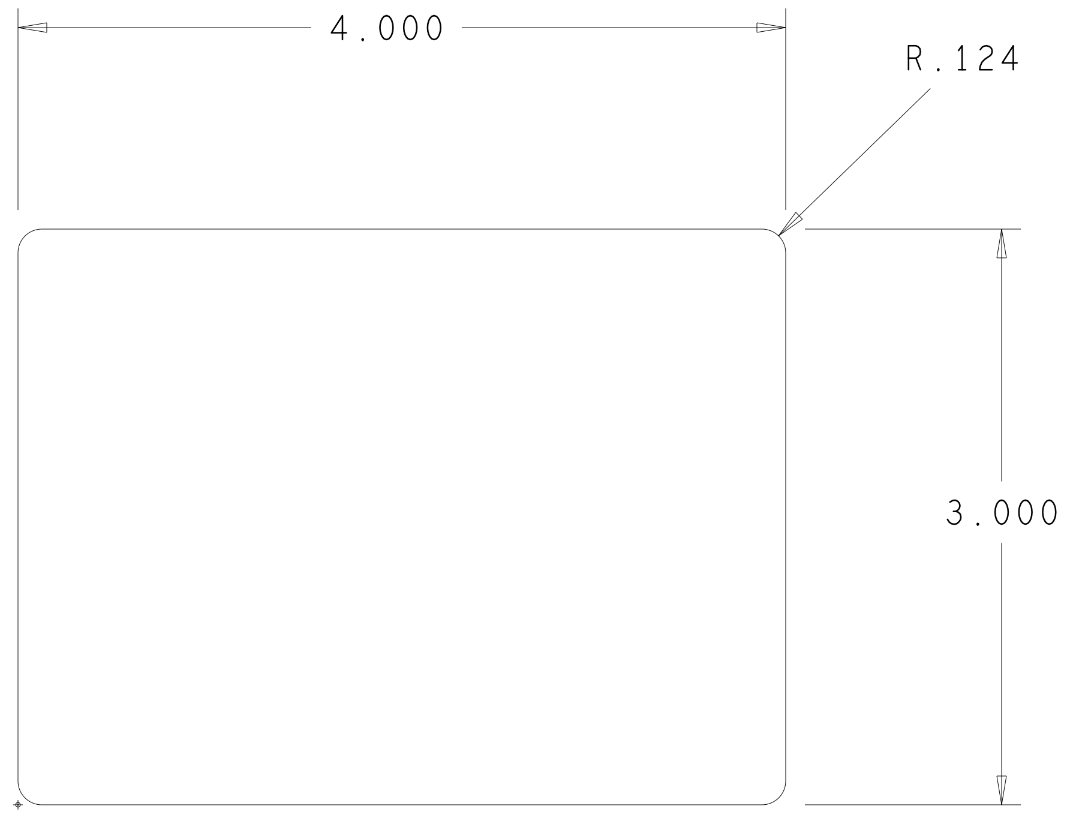
TABLE 1:

LAYER NO.	LAYER NAME	DIFFIRENTIAL PAIR IMPEDANCE (OHMS)	DIFF TRACE WIDTH	DIFF TRACE SPACING	SINGLE ENDED IMPEDANCE (OHMS)	SINGLE ENDED TRACE WIDTH	REFERENCE LAYER
LAYER 1	TOP				60 +/- 10%	0.011"	LAYER 2
LAYER 2	L2_GND						
LAYER 3	L3_PWR						
LAYER 4	BOTTOM				60 +/- 10%	0.011"	LAYER 3

SPECIAL FAB NOTES:

1:FAB SHOP MUST FOLLOW THE SOLDER MASK REVIEW LAYERS.
2:

PLACE DRILL CHART HERE:



CAD ORIGIN

krypton solutions	BOARD NAME: XXXXXXXX	BOARD REV: 1.0	KSID: XXXXX	JOB NUMBER: XXXXXX
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: FABRICATION DRAWING		

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
NUMBER OF LAYERS: X
MIN. TRACK WIDTH: X.X MIL
MIN. CLEARANCE : X.X MIL
MIN. VIA PAD/DRILL: XX/XX MIL

MIN. ANNULAR RING 2 MIL EXTERNAL PER IPC-6012C CLASS 2
REGISTRATION TOLERANCES: METAL +/- X MIL,HOLES +/- X MIL
IMPEDANCE CONTROL: ☐ NONE ☒ YES - SEE TABLE 1
MIXED DIELECTRIC: ☒ NO ☐ YES
LAMINATE MATERIAL:
☒ FR-4 HIGH Tg ☐ ROGERS 4350B ☐ OTHER: ____
THICKNESS:
☒ 0.062" +/-10% ☐ 0.093" +/-10% ☐ OTHER: ____
TOLERANCE:
☒ IPC-6012C TYPE 3 CLASS 2
☐ OTHER +/-
BOW & TWIST:
☒ IPC-6012C TYPE 3 CLASS 2
☐ OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1/4 OZ. ☐ 1/2 OZ. ☒ 1.0 OZ. ☐ 2.0 OZ.
INNER SIGNAL: ☐ 1/4 OZ. ☐ 1/2 OZ. ☐ 1.0 OZ. ☐ 2.0 OZ.
INNER PLANE: ☐ 1/4 OZ. ☐ 1/2 OZ. ☒ 1.0 OZ. ☐ 2.0 OZ.
OTHER: ____
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ____
SOLDERMASK: (PER IPC-6011,6012)
☒ TOP ☒ BOTTOM
SOLDERMASK COLOR: ☒ GREEN ☐ BLUE ☐ OTHER ____
THROUGH-HOLE VIA TREATMENT:
☒ OPEN ☐ TENTED IDENTIFIER: ALL x MIL VIAS
VIA FILL USING NON-CONDUCTIVE EPOXY:
☒ NO ☐ YES IDENTIFIER: ALL x MIL VIAS
THIEVING ALLOWED: ☒ YES ☐ NO
BOARD SURFACE TREATMENT:
☒ NICKEL/GOLD (ENIG) ☐ ORGANIC (OSP) ☐ HASL ☐ ENEPIG
☐ IMMERSION TIN ☐ OTHER ____
FOR WIRE BONDING:
☐ HARD GOLD ☐ SOFT GOLD ☐ PER SUPPLIED ARTWORK
ADDITIONAL REQUIREMENTS:
☒ MICRO-SECTION ☒ TDR REPORTS/COUPONS ☒ ELECTRICAL TEST
☒ CERTIFICATES OF COMPLIANCE ☒ RoHS ☒ UL 94V-0
VENDOR MARKING:
VENDOR DATE CODE,UL,LOGO: ☐ ETCH ☒ SILKSCREEN ☐ BREAK-AWAY
☒ IN AN OPEN AREA ☐ WHERE INDICATED (SEE DRAWING)

krypton solutions

CUSTOMER XXXXXXXXXXXX			ENGINEER XXXXX	
BOARD NAME : XXXXXXXXXXXXXXX				
FABRICATION DRAWING				
APPROVALS	DATE	SIZE D	KSID NO. XXXXX	JOB NO. XXXXXX
DRAWN: xxx	xx-xx-xx			REV. 1.0
RELEASED: xxx	xx-xx-xx			
DO NOT SCALE DRAWING		SCALE NONE		SHEET 1 OF 1

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